OKI Semiconductor MSM7704-01/02/03

# 2ch Single Rail CODEC

# **GENERAL DESCRIPTION**

The MSM7704-01/7704-02/7704-03 are two-channel CODEC CMOSICs for voice signals ranging from 300 to 3400 Hz. These devices contain filters for A/D and D/A conversion.

Designed especially for a single-power supply and low-power applications, these devices contain two-channel AD/DA converters in a single chip and achieve a reduced footprint and a reduced number of external components.

The MSM7704-01/7704-02/7704-03 are best suited for an analog interface to an echo canceller DSP used in digital telephone terminals, digital PABXs, and hands free terminals.

## FEATURES

• Single power supply: +2.7 V to +3.8 V

<ul> <li>Power consumption</li> </ul>		
Operating mode:	30 mW Typ.	50 mW Max.
Power-saving mode:	3 mW Typ.	6 mW Max.
Power-down mode:	0.03 mW Typ.	0.3 mW Max.

- ITU-T Companding law MSM7704-01: μ/A-law pin-selectable MSM7704-02: μ-law MSM7704-03: A-law
- Built-in PLL eliminates a master clock
- The PCM interface can be switched between 2 channel serial/parallel
- Transmission clock: 64/128/256/512/1024/2048 kHz

96/192/384/768/1536/1544/200 kHz

(During 2 channel serial mode, the 64 and 96 kHz clocks are disabled)

- Adjustable transmit gain
- Built-in reference voltage supply
- Analog output can directly drive a 1.2  $k\Omega$  load
- Package:

24-pin plastic SOP (SOP24-P-430-1.27-K) (Product name : MSM7704-01GS-K)

(Product name : MSM7704-02GS-K)

(Product name : MSM7704-03GS-K)

# **BLOCK DIAGRAM**



# **PIN CONFIGURATION (TOP VIEW)**





\* The ALAW pin is only applied to the MSM7704-01GS-K.

# PIN AND FUNCTIONAL DESCRIPTIONS

#### AIN1, AIN2, GSX1, GSX2

AIN1 and AIN2 are the transmit analog inputs for channels 1 and 2.

GSX1 and GSX2 are the transmit level adjustments for channels 1 and 2.

AIN1 and AIN2 are inverting inputs for the op-amps. GSX1 and GSX2 are connected to the outputs of the op-amps and are used to adjust the level, as shown below.

When AIN1 and AIN2 are not used, connect AIN1 to GSX1 and AIN2 to GSX2. During power saving mode and power down mode, the GSX1 and GSX2 outputs are in high impedance state.



#### AOUT1, AOUT2

AOUT1 is the receive analog output for channel 1 and AOUT2 is used for channel 2. The output signal has an amplitude of 2.0  $V_{PP}$  above and below the signal ground voltage (SG :  $1/2 V_{DD}$ ). When the digital signal of +3 dBmO is input to DIN1 and DIN2, it can drive a load of 1.2 k $\Omega$  or more.

During power saving mode, or power down mode, these outputs are at the voltage level of SG with a high impedance.

# $V_{DD}$

Power supply for +3 V.

A power supply for an analog circuit in the system to which the device is applied should be used. A bypass capacitor of  $0.1 \,\mu\text{F}$  to  $1 \,\mu\text{F}$  with excellent high-frequency characteristics and a capacitor of  $10 \,\mu\text{F}$  to  $20 \,\mu\text{F}$  should be connected between this pin and the AG pin if needed.

#### DIN1

PCM signal input for channel 1 when the parallel mode is selected.

D/A conversion is performed with the serial PCM signal input to this pin, the RSYNC signal synchronous with the serial PCM signal, and the BCLK signal, and then the analog output is output from AOUT1 pin.

The data rate of the PCM signal is equal to the frequency of the BCLK signal.

The PCM signal is shifted at the falling edge of the BCLK signal and latched into the internal register when shifted by eight bits.

The start of the PCM data (MSD) is identified at the rising edge of RSYNC.

When the serial mode is selected, this pin is not used and should be connected to GND (0 V).

## DIN2

PCM signal input for channel 2 when the parallel mode is selected.

D/A conversion is performed with the serial PCM signal input to this pin, the RSYNC signal synchronous with the serial PCM signal, and the BCLK signal, and then the analog output is output from AOUT2 pin.

The data rate of the PCM signal is equal to the frequency of the BCLK signal.

The PCM signal is shifted at the falling edge of the BCLK signal and latched into the internal register when shifted by eight bits.

The start of the PCM data (MSD) is identified at the rising edge of RSYNC.

When the serial mode is selected, this pin is used for the 2ch multiplexed PCM signal input.

#### BCLK

Shift clock signal input for the DIN1, DIN2, DOUT1, and DOUT2 signals.

The frequency, equal to the data rate, is 64, 96, 128, 192, 256, 384, 512, 768, 1024, 1536, 1544, 2048, or 200 kHz. Setting this signal to logic "1" or "0" drives both transmit and receive circuits to the power saving state.

#### RSYNC

Receive synchronizing signal input.

Eight bits PCM data required are selected from a series of PCM signal to the DIN1 and DIN2 pins by the receive synchronizing signal.

All timing signals in the receive section are synchronized by this synchronizing signal. This signal must be synchronized in phase with the BCLK (generated from the same clock source as BCLK). The frequency should be 8 kHz ±50 ppm to guarantee the AC characteristics which are mainly the frequency characteristics of the receive section.

However, unless the frequency characteristics of the system used are strictly specified, this device can operate in the range of 6 kHz to 9 kHz, but the electrical characteristics specified in the data sheet are not guaranteed.

#### XSYNC

Transmit synchronizing signal input.

PCM output signal from the DOUT1 and DOUT2 pins is output in synchronization with this transmit synchronizing signal. This synchronizing signal triggers the PLL and synchronizes all timing signals of the transmit section.

This synchronizing signal must be synchronized in phase with BCLK.

The frequency should be 8 kHz  $\pm$ 50 ppm to guarantee the AC characteristics which are mainly the frequency characteristics of the transmit section.

However, unless the frequency characteristics of the system used are strictly specified, this device can operate in the range of 6 kHz to 9 kHz, but the electrical characteristics are not guaranteed.

Setting this signal to logic "1" or "0" drives both transmit and receive circuits to power saving state.

# DOUT1

PCM signal output of channel 1 when the parallel mode is selected.

The PCM output signal is output from MSD in a sequential order, synchronizing with the rising edge of the BCLK signal.

MSD may be output at the rising edge of the XSYNC signal, based on the timing between BCLK and XSYNC.

This pin is in a high impedance state except during 8-bit PCM output. It is also in a high impedance state during power-saving state or power-down state.

When the serial mode is selected, this pin is configured to be the output of serial multiplexed 2ch PCM signal.

A pull-up resistor must be connected to this pin because it is an open drain output.

This device is compatible with the ITU-T recommendation on coding law and output coding format.

The MSM7704-03 (A-law) outputs the character signal, inverting the even bits.

1	PCMIN/PCMOUT							
Input/Output Level	MSM7704-02 (μ-law)	MSM7704-03 (A-law)						
	MSD	MSD						
+Full scale	1 0 0 0 0 0 0	1 0 1 0 1 0 1 0						
+0	1 1 1 1 1 1 1 1	1 1 0 1 0 1 0 1						
-0	0 1 1 1 1 1 1 1	0 1 0 1 0 1 0 1						
–Full scale	0 0 0 0 0 0 0 0	0 0 1 0 1 0 1 0						

#### DOUT2

PCM signal output for channel 2 when the parallel mode is selected.

The PCM output signal is output from MSD in a sequential order, at the rising edge of the BCLK signal.

MSD may be output at the rising edge of the XSYNC signal, based on the timing between BCLK and XSYNC.

This pin is in a high impedance state except during 8-bit PCM output. It is also in a high impedance state during power-saving state or power-down state.

When the serial mode is selected, this pin is left open.

A pull-up resistor must be connected to this pin because it is an open drain output.

This device is compatible with the ITU-T recommendation on coding law and output coding format.

The MSM7704-03 (A-law) outputs the character signal inverting the even bits.

# CHPS

Control signal input for the mode selection of PCM input and output.

When this signal is at a logic "1" level, the PCM input and output are in the parallel mode. The PCM data of CH1 and CH2 is input to DIN1 and DIN2 and output from DOUT1 and DOUT2 with the same timing.

When this signal is at a logic "0" level, the PCM input and output are in the serial mode. The PCM data of CH1 and CH2 is input to DIN2 and output from DOUT1 as time division multiplexed data.

The parallel mode is conveniently applied to the digital interface to the echo canceller device, and the serial mode is applied to the digital interface to PCM multiplexer's for PABXs.

#### PDN

Power down control signal. When PDN is at a logic "0" level, both transmit and receive circuits are in power down state.

# AG

Analog signal ground.

#### DG

Ground for the digital signal circuits.

This ground is separate from the analog signal ground. The DG pin must be connected to the AG pin on the printed circuit board to make a common analog ground.

#### SGC

Used to generate the signal ground voltage level by connecting a bypass capacitor. Connect a  $0.1\,\mu F$  capacitor with excellent high frequency characteristics between the AG pin and the SGC pin.

#### ALAW

Control signal input of the companding law selection.

Provides only for the MSM7704-01GS-K. The CODEC will operate in the  $\mu$ -law when this pin is at a logic "0" level and the CODEC will operate in the A-law when this pin is at a logic "1" level. The CODEC operates in the  $\mu$ -law if the pin is left open, since this pin is internally pulled down.

# ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V <sub>DD</sub>	—	0 to 7	V
Analog Input Voltage	V <sub>AIN</sub>	_	-0.3 to V <sub>DD</sub> + 0.3	V
Digital Input Voltage	V <sub>DIN</sub>	_	-0.3 to V <sub>DD</sub> + 0.3	V
Storage Temperature	T <sub>STG</sub>	_	-55 to +150	°C

# **RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	V <sub>DD</sub>	Voltage must be fixed	2.7	3.0	3.8	V
Operating Temperature	Та		-30	+25	+85	°C
Analog Input Voltage	V <sub>AIN</sub>	Gain = 1	—	—	1.4	$V_{PP}$
Digital Input High Voltage	VIH	XSYNC, RSYNC, BCLK, DIN1,	$0.45  imes V_{DD}$	—	V <sub>DD</sub>	V
Digital Input Low Voltage	V <sub>IL</sub>	DIN2, PDN, CHPS	0	_	$0.16  imes V_{DD}$	V
Clock Frequency	F <sub>C</sub>	BCLK = (eliminates 64, 96 kHz, when 2ch serial mode) 64, 128, 256, 512, 1024, 2048, 96, 192, 384, 768, 1536, 1544, 200				kHz
Sync Pulse Frequency	F <sub>S</sub>	XSYNC, RSYNC	_	8.0	_	kHz
Clock Duty Ratio	D <sub>C</sub>	BCLK	40	50	60	%
Digital Input Rise Time	t <sub>lr</sub>	XSYNC, RSYNC, BCLK, DIN1,	_	_	50	ns
Digital Input Fall Time	t <sub>lf</sub>	DIN2, PDN, CHPS	—	_	50	ns
Transmit Suna Dulas Satting Time	t <sub>XS</sub>	BCLK $\rightarrow$ XSYNC, See Timing Diagram	100			ns
Transmit Sync Pulse Setting Time	t <sub>SX</sub>	$\textbf{XSYNC} {\rightarrow} \textbf{BCLK}, \textbf{See Timing Diagram}$	100		—	ns
Dessive Supe Dules Setting Time	t <sub>RS</sub>	$BCLK \rightarrow RSYNC$ , See Timing Diagram	100	—		ns
Receive Sync Pulse Setting Time	t <sub>SR</sub>	$RSYNC {\rightarrow} BCLK,  See \ Timing \ Diagram$	100	—	—	ns
Sync Pulse Width	t <sub>WS</sub>	XSYNC, RSYNC	1 BCLK	_	100	μs
DIN Set-up Time	t <sub>DS</sub>	DIN1, DIN2	100			ns
DIN Hold Time	t <sub>DH</sub>	DIN1, DIN2	100		—	ns
Digital Output Load	R <sub>DL</sub>	Pull-up resistor, DOUT1, DOUT2	0.5		_	kΩ
Digital Output Load	C <sub>DL</sub>	DOUT1, DOUT2	—		100	рF
Analog Input Allowable DC Offect		Transmit gain stage, Gain = 1	V <sub>DD</sub> /2 –100		V <sub>DD</sub> /2 +100	mV
Analog Input Allowable DC Offset	Voff	Transmit gain stage, Gain = 10	V <sub>DD</sub> /2 -10		V <sub>DD</sub> /2 +10	mV
Allowable Jitter Width		XSYNC, RSYNC	—		500	ns

# **ELECTRICAL CHARACTERISTICS**

#### **DC and Digital Interface Characteristics**

-		(V <sub>DE</sub>	) = 2.7 V to	3.8 V, Ta	= -30°C to	+85°C)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
	I <sub>DD1</sub>	Operating mode, No signal		10.0	14.0	mA
Power Supply Current	I <sub>DD2</sub>	Power-save mode, PDN = 1, XSYNC or BCLK OFF	_	1.0	4.0	mA
	I <sub>DD3</sub>	Power-down mode, PDN = 0 Digital input is at 0 V	_	0.01	0.05	mA
Input High Voltage	VIH	—	$0.45 \times V_{\text{DD}}$	_	V <sub>DD</sub>	V
Input Low Voltage	VIL	—	0.0	—	$0.16  imes V_{DD}$	V
High Level Input Leakage Current	I <sub>IH</sub>	—	—		2.0	μA
Low Level Input Leakage Current	IIL	—	—		0.5	μA
Digital Output Low Voltage	V <sub>OL</sub>	Pull-up resistance > 500 $\Omega$	0.0	0.2	0.4	V
Digital Output Leakage Current	I <sub>0</sub>	—			10	μA
Input Capacitance	CIN		—	5	—	рF

#### **Transmit Analog Interface Characteristics**

 $(V_{DD} = 2.7 \text{ V to } 3.8 \text{ V}, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$ 

	·				,		
Parameter	Symbol	Cond	Min.	Тур.	Max.	Unit	
Input Resistance	R <sub>INX</sub>	AIN1, AIN2	10	—		MΩ	
Output Load Resistance	R <sub>LGX</sub>	GSX1, GSX2	20	_	_	kΩ	
Output Load Capacitance	CLGX	with respect to	with respect to SG			30	pF
Output Amplitude	V <sub>OGX</sub>			-0.7	_	+0.7	V
Offset Voltage	V <sub>OSGX</sub>		Gain = 1	-20	_	+20	mV

#### **Receive Analog Interface Characteristics**

A/ .	0 7 1/	+~ 2 0	11	То	າທາດ	+0	.0500	`
$(V_{DD} = 1)$	2.1 V	10 3.0	ν,	1a =	-30 0	10	+00 0	)

						<u>,                                     </u>
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Output Load Resistance	п	AOUT1, AOUT2 (each) with	10			10
	R <sub>LAO</sub>	respect to SG	1.2			kΩ
Output Load Capacitance	CLAO	AOUT1, AOUT2	_	—	50	pF
Output Amplitude	V <sub>OAO</sub>	AOUT1, AOUT2, $R_L$ = 1.2 k $\Omega$	4	_	+1	v
Output Amplitude		with respect to SG	-1			
Offset Voltage		AOUT1, AOUT2 with respect	100	_	+100	m\/
	Vosao	to SG	-100			mV

#### **AC Characteristics**

Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	Loss T1	60			20	26		dB
	Loss T2	300	1		-0.15	+0.07	+0.20	dB
Transmit Francisco Deservado	Loss T3	1020				Reference		dB
Transmit Frequency Response	Loss T4	2020	0		-0.15	-0.04	+0.20	dB
	Loss T5	3000	]		-0.15	+0.06	+0.20	dB
	Loss T6	3400	]		0	0.4	0.80	dB
	Loss R1	300			-0.15	-0.03	+0.20	dB
	Loss R2	1020				Reference		dB
Receive Frequency Response	Loss R3	2020	0		-0.15	+0.02	+0.20	dB
	Loss R4	3000	]		-0.15	+0.12	+0.20	dB
	Loss R5	3400	]		0.0	0.46	0.80	dB
Transmit Signal to Distortion Ratio	SD T1		3		35	43	—	
	SD T2		0		35	41	_	
	SD T3	1020	-30		35	38		dB
	SD T4		-40	*1	28	31.5	—	
	SD T5		-45		23	27		
	SD R1		3		36	43		
	SD R2		0		36	41		
Receive Signal to Distortion Ratio	SD R3	1020	-30		36	40	—	dB
	SD R4		-40	*1	30	33.5		_
	SD R5		-45		25	30	—	
	GT T1		3		-0.3	+0.01	+0.3	
	GT T2		-10			Reference		
Transmit Gain Tracking	GT T3	1020	-40		-0.3	0	+0.3	dB
	GT T4		-50		-0.5	-0.03	+0.5	
	GT T5		-55		-1.2	-0.05	+1.2	
	GT R1		3		-0.3	-0.06	+0.3	
	GT R2		-10			Reference		
Receive Gain Tracking	GT R3		-40		-0.4	+0.2	+0.4	
	GT R4	1020	50	*2	1.0	+0.62		dB
	GI K4		-50	2	-1.0	+0.20	+1.0	
	CT DE		EE	*0	1 0	+0.65	.10	
	GT R5	-55 *2	-1.2	+0.3	+1.2			

\*1 Psophometric filter is used

\*2 Upper is specified for the  $\mu$ -law, lower for the A-law

#### **AC Characteristics (Continued)**

$(V_{DD} = 2.7 \text{ V to } 3.8 \text{ V}, \text{ Ta} = -30^{\circ}\text{C}$	) to	+85°	'C)
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				,				
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	Nielle T			AIN = SG		-73.5	-69	
Idle Channel Noise	Nidle T	_	_	*1 *2	_	-71.5	-68	dBmOp
	NidleR	—	—	*1 *3	—	-76	-74	
Absolute Level (Initial Difference)	AV T			V <sub>DD</sub> = 3.0 V Ta = 25°C	0.338	0.350	0.362	Vrms
	AV R			*4	0.483	0.500	0.518	VIIIIS
Absolute Level	AV Tt	1020	0	V <sub>DD</sub> = 2.7 V to 3.8 V	-0.2	_	+0.2	dB
(Deviation of Temperature and Power)	AV Rt			Ta = -30 to +85°C *4	-0.2	—	+0.2	dB
Absolute Delay	Td	1020	0	A to A BCLK = 64 kHz	_	_	0.60	ms
	t <sub>gd</sub> T1	500		*5	_	0.19	0.75	
	t <sub>gd</sub> T2	600				0.11	0.35	
Transmit Group Delay	t <sub>gd</sub> T3	1000	0			0.02	0.125	ms
	t <sub>gd</sub> T4	2600			_	0.05	0.125	
	t <sub>gd</sub> T5	2800			—	0.07	0.75	
	t <sub>gd</sub> R1	500		*5	—	0.00	0.75	
	t <sub>gd</sub> R2	600			_	0.00	0.35	
Receive Group Delay	t <sub>gd</sub> R3	1000	0		—	0.00	0.125	ms
	t <sub>gd</sub> R4	2600			—	0.09	0.125	
	t <sub>gd</sub> R5	2800			_	0.12	0.75	
	CR T			$\text{TRANS} \rightarrow \text{RECV}$	75	80	_	
Crosstalk Attenuation	CR R	1020	0	$\text{RECV} \rightarrow \text{TRANS}$	70	76		dB
	CR CH			CH to CH	75	80	_	

\*1 Psophometric filter is used

\*2 Upper is specified for the  $\mu$ -law, lower for the A-law

\*3 Input "0" code to PCMIN

\*4 AVT is defined between GSX and DOUT and AVR between DIN and AOUT

\*5 Minimum value of the group delay distortion

# AC Characteristics (Continued)

Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
Discrimination	DIS	4.6 kHz to	0	0 to	30	32	_	dB
		72 kHz		4000 Hz				
Out-of-band Spurious	S	300 to 3400	0	4.6 kHz to 100 kHz	—	-37.5	-35	dBmO
Intermodulation Distortion	IMD	fa = 470	-4	2fa – fb	_	-52	-35	dBmO
		fb = 320						
Power Supply Noise Rejection Ratio	PSR T	0 to	50 mV <sub>PP</sub>	*6	_	30	_	dB
	PSR R	50 kHz						
Digital Output Delay Time	t <sub>SD</sub>	C <sub>L</sub> = 100 pF + 1 LSTTL			20	—	200	ns
	t <sub>XD1</sub>				20		200	
	t <sub>XD2</sub>				20	_	200	
	t <sub>XD3</sub>				20	_	200	

\*6 The measurement under idle channel noise

## TIMING DIAGRAM

#### **Transmit Timing**



Figure 2 Timing Diagram in the Serial Mode (CHPS = 0)

# **APPLICATION CIRCUIT**

#### Example of Basic Connection (PCM Serial Mode Operation)



#### **PCM Parallel Mode**



The AOUT1 and AOUT2 output signals swing  $\pm 1.0$  V above and below the offset level of  $V_{DD}/$  2.

# **RECOMMENDATIONS FOR ACTUAL DESIGN**

- To assure proper electrical characteristics, use bypass capacitors with excellent high frequency characteristics for the power supply and keep them as close as possible to the device pins.
- Connect the AG pin and the DG pin each other as close as possible. Connect to the system ground with low impedance.
- Mount the device directly on the board when mounted on PCBs. Do not use IC sockets. If an IC socket is unavoidable, use the short lead type socket.
- When mounted on a frame, use electro-magnetic shielding, if any electro-magnetic wave source such as power supply transformers surround the device.
- Keep the voltage on the V<sub>DD</sub> pin not lower than –0.3 V even instantaneously to avoid latchup phenomenon when turning the power on.
- Use a low noise (particularly, low level type of high frequency spike noise or pulse noise) power supply to avoid erroneous operation and the degradation of the characteristics of these devices.

# PACKAGE DIMENSIONS

(Unit : mm)



Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, SOJ, QFJ (PLCC), SHP and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).